

F

E

D

C

B

A

F

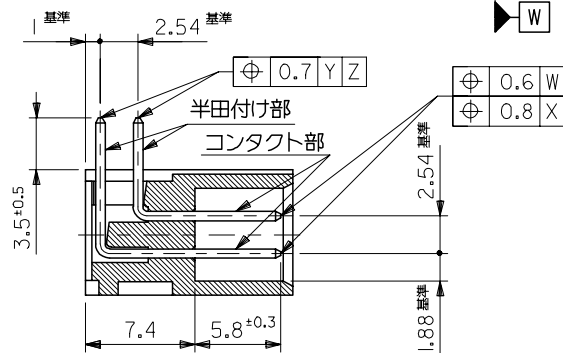
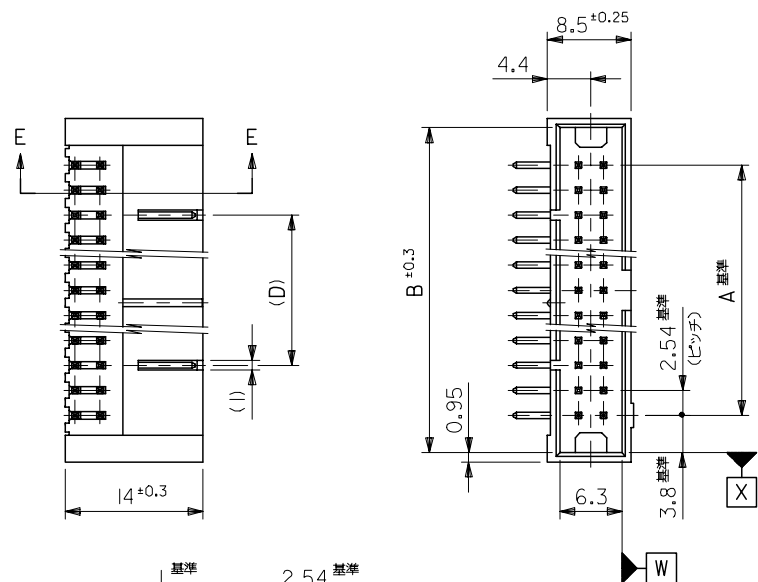
E

D

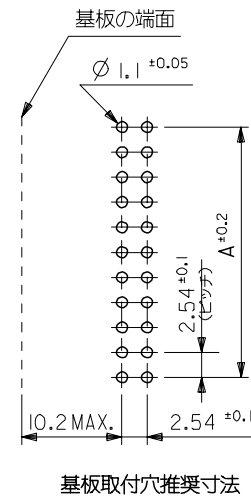
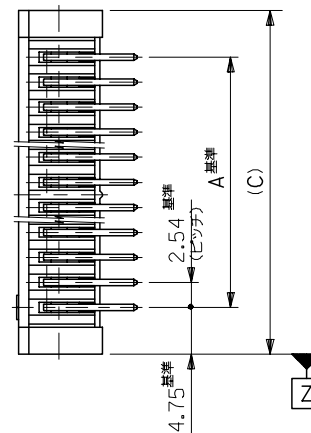
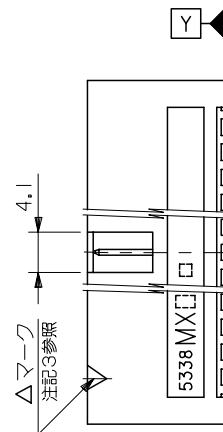
C

B

A



SECT. E-E (SCALE 3-1)



注記

- 材料 ウエハー : ガラス繊維 I5% 入り PBTP (UL94V-0), 黒色
ピン : 黄銅, サイズ □0.635
- 嵌合相手 : 5320 シリーズ
- 使用符号の説明

5342 - N *

ベースナンバー _____

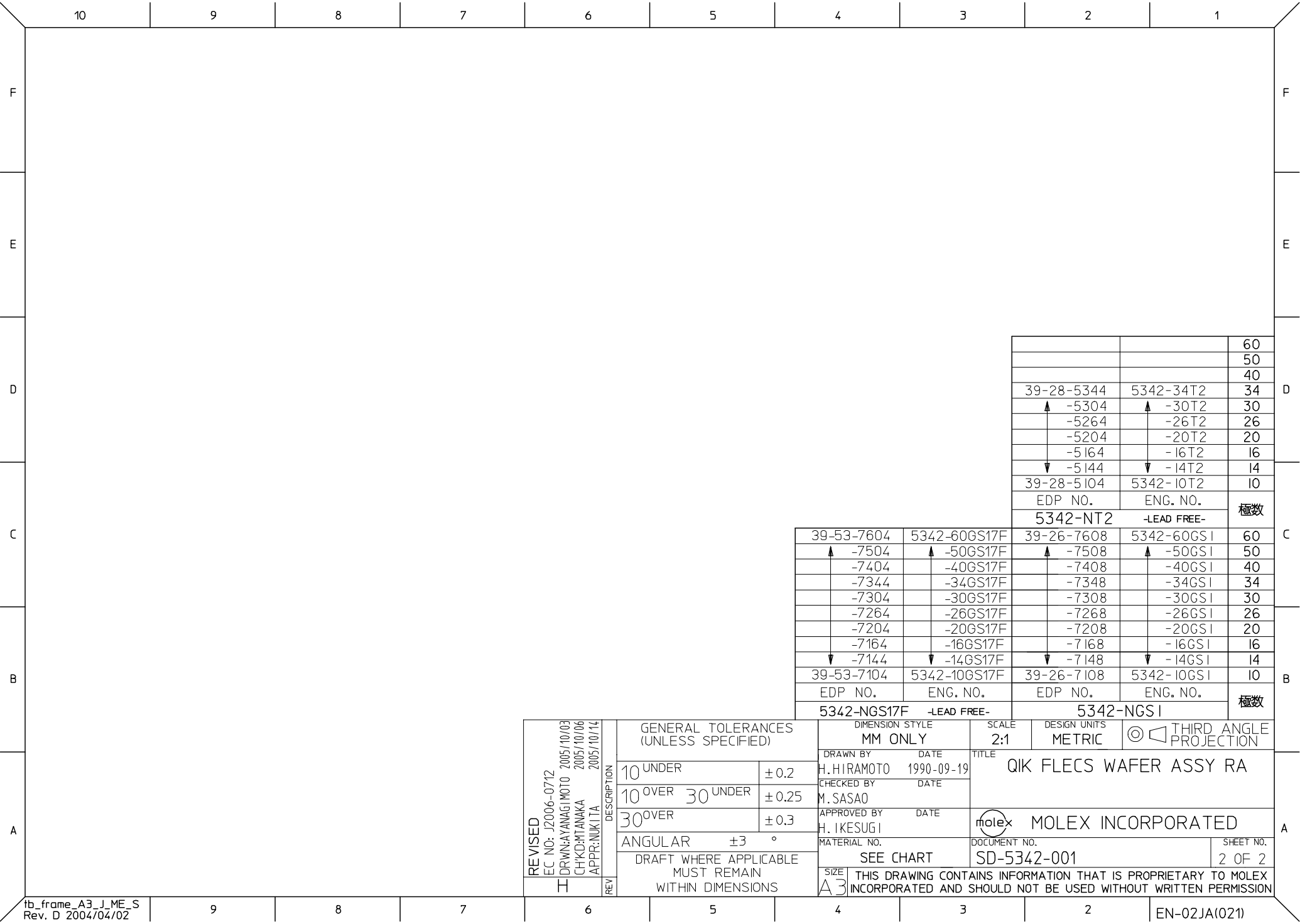
極数 _____

ピンのメッキコード _____

コード:*	Δマークの色	コンタクト部	半田付け部	下地メッキ
GS1	黄	金 0.1μm MIN.	半田 3μm MIN.	ニッケル 1μm MIN.
LEAD-FREE GS17F	黄	金 0.1μm MIN.	錫 1μm MIN.	ニッケル 1μm MIN.
LEAD-FREE T2	黒	錫 1μm MIN.		ニッケル 0.5μm MIN.

60	73.66	81.26	83.16	63.50
50	60.96	68.56	70.46	50.80
40	48.26	55.86	57.76	38.10
34	40.64	48.24	50.14	30.48
30	35.56	43.16	45.06	25.40
26	30.48	38.08	39.98	—
20	22.86	30.46	32.36	—
16	17.78	25.38	27.28	—
14	15.24	22.84	24.74	—
10	10.16	17.76	19.66	—
極数	A 寸法	B 寸法	C 寸法	D 寸法

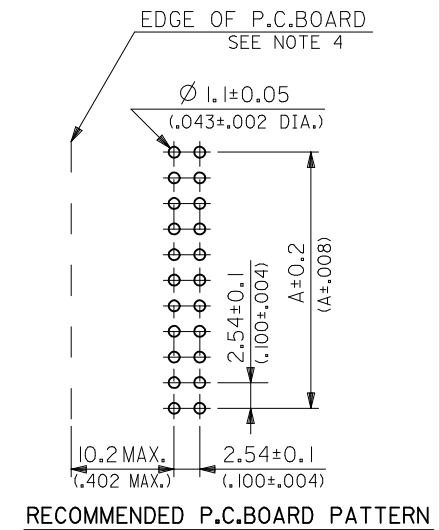
REVISED EC NO: J2006-0712 DRWN: YANAGI MOTO 2005/10/03 CHKD: TANAKA 2005/10/06 APPR: NUKITA 2005/10/14	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY H. HIRAMOTO	DATE 1990/06/19	TITLE QIK FLECS WAFER ASSY RA			
		10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE				
		30 OVER	±0.3	APPROVED BY H. IKESUGI	DATE	MOLEX INCORPORATED			
		ANGULAR ±3 °		MATERIAL NO.					
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 2 OF 2		SD-5342-001			1 OF 2	
1	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



		60
		50
		40
39-28-5344	5342-34T2	34
▲ -5304	▲ -30T2	30
-5264	-26T2	26
-5204	-20T2	20
-5164	-16T2	16
▼ -5144	▼ -14T2	14
39-28-5104	5342-10T2	10
EDP NO.	ENG. NO.	
5342-NT2	-LEAD FREE-	極数

39-53-7604	5342-60GS17F	39-26-7608	5342-60GS1	60
▲ -7504	▲ -50GS17F	▲ -7508	▲ -50GS1	50
-7404	-40GS17F	-7408	-40GS1	40
-7344	-34GS17F	-7348	-34GS1	34
-7304	-30GS17F	-7308	-30GS1	30
-7264	-26GS17F	-7268	-26GS1	26
-7204	-20GS17F	-7208	-20GS1	20
-7164	-16GS17F	-7168	-16GS1	16
▼ -7144	▼ -14GS17F	▼ -7148	▼ -14GS1	14
39-53-7104	5342-10GS17F	39-26-7108	5342-10GS1	10
EDP NO.	ENG. NO.	EDP NO.	ENG. NO.	
5342-NGS17F	-LEAD FREE-	5342-NGS1		極数

REVISED EC NO: J2006-0712 DRWN:YANAGIMOTO 2005/10/03 CHKD:MTANAKA 2005/10/06 APPR:NUKITA 2005/10/14	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY H.HIRAMOTO	DATE 1990-09-19	TITLE QIK FLECS WAFER ASSY RA				
		10 OVER 30 UNDER	±0.25	CHECKED BY M.SASAO	DATE					
		30 OVER	±0.3	APPROVED BY H. IKESUGI	DATE	MOLEX INCORPORATED				
		ANGULAR	±3 °	MATERIAL NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-5342-001		2 OF 2		
		REV		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



- BASE NUMBER _____
CIRCUIT SIZE _____
PLATING CODE OF PIN _____

	CODE**	△ MARK COLOR	CONTACT AREA	SOLDER AREA	UNDER PLATE
LEAD-FREE	GS17F	YELLOW	GOLD 0.1 μm(.000004) MIN.	TIN 1 μm(.00004) MIN.	NICKEL 1 μm(.00004) MIN.
LEAD-FREE	T2	BLACK	TIN 1 μm(.00004) MIN.		NICKEL 0.5 μm(.00002) MIN.

4. 10.2(.402) MAX. TO EDGE OF P.C. BOARD FOR DAISY CHAIN APPLICATION.

SECT. E-E (SCALE 3:1)

60	73.66 (2.900)	81.26 (3.200)	83.16 (3.274)	63.50 (2.500)
50	60.96 (2.400)	68.56 (2.700)	70.46 (2.774)	50.80 (2.000)
40	48.26 (1.900)	55.86 (2.200)	57.76 (2.274)	38.10 (1.500)
36	43.18 (1.700)	50.78 (2.000)	52.68 (2.074)	33.02 (1.300)
34	40.64 (1.600)	48.24 (1.900)	50.14 (1.974)	30.48 (1.200)
30	35.56 (1.400)	43.16 (1.700)	45.06 (1.774)	25.40 (1.000)
26	30.48 (1.200)	38.08 (1.500)	39.98 (1.574)	—————
20	22.86 (.900)	30.46 (1.200)	32.36 (1.274)	—————
16	17.78 (.700)	25.38 (1.000)	27.28 (1.074)	—————
14	15.24 (.600)	22.84 (.900)	24.74 (.974)	—————
10	10.16 (.400)	17.76 (.700)	19.66 (.774)	—————
NO. OF CKTS.	DIM. A	DIM. B	DIM. C	DIM. D

REVISED	EC NO: J2009-2013 DRWN:MMABEI CHKD:THIRUYANA APPR:NUKITA	2009/03/12 2009/03/13 2009/03/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE 2:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
				10 UNDER	± 0.2	DRAWN BY H. HIRAMOTO	DATE 1989/08/21	TITLE QIK FLECS WAFER ASSY RA		
				10 OVER 30 UNDER	± 0.25	CHECKED BY M. SASAO	DATE			
				30 OVER	± 0.3	APPROVED BY H. IKESUGI	DATE	 MOLEX INCORPORATED		
				ANGULAR ±3 °		MATERIAL NO.	DOCUMENT NO.			
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	SEE SHEET 2 SD-5342-002 1 OF 2			
REV				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

10 9 8 7 6 5 4 3 2 1

F

F

E

E

D

D

C

C

B

B

A

A

—#—	—#—	39-53-7504	5342-50GS17F	50
—#—	—#—	▲ -7404	▲ -40GS17F	40
—#—	—#—	—#—	—#—	36
39-28-5344	5342-34T2	—#—	—#—	34
▲ -5304	▲ -30T2	-7304	-30GS17F	30
-5264	-26T2	-7264	-26GS17F	26
-5204	-20T2	-7204	-20GS17F	20
▼ -5164	▼ -16T2	-7164	-16GS17F	16
▼ -5144	▼ -14T2	▼ —#—	▼ —#—	14
39-28-5104	5342-10T2	39-53-7104	5342-10GS17F	10
EDP NO.	ENG. NO.	EDP NO.	ENG. NO.	NO. OF
5342-NT2	-LEAD FREE-	5342-NGS17F	-LEAD FREE-	CKTS.

REVISED EC NO: J2009-2013 DRWN:MNABEI 2009/03/12 CHKD:THARUYAMA 2009/03/13 APPR:NUKITA 2009/03/16 K	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY H. HIRAMOTO	DATE 1989/08/21	TITLE QIK FLECS WAFER ASSY RA				
		10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE					
		30 OVER	±0.3	APPROVED BY H. IKESUGI	DATE	MOLEX INCORPORATED				
		ANGULAR ±3 °		MATERIAL NO.						
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-5342-002		2 OF 2			
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							